Preferred Device

## **Silicon Controlled Rectifiers**

## **Reverse Blocking Thyristors**

Designed primarily for half-wave ac control applications, such as motor controls, heating controls and power supplies.

- Glass Passivated Junctions with Center Gate Geometry for Greater Parameter Uniformity and Stability
- Small, Rugged, Thermowatt Construction for Low Thermal Resistance, High Heat Dissipation and Durability
- Blocking Voltage to 800 Volts
- Device Marking: Logo, Device Type, e.g., 2N6394, Date Code

#### \*MAXIMUM RATINGS (T<sub>J</sub> = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit		
Peak Repetitive Off–State Voltage (Note 1.) (T <sub>J</sub> = -40 to 125°C, Sine Wave, 50 to 60 Hz, Gate Open)	V <sub>DRM</sub> , V <sub>RRM</sub>		Volts		
2N6394 2N6395 2N6397 2N6399	075C.	50 100 400 800			
On-State RMS Current (180° Conduction Angles; T <sub>C</sub> = 90°C)	I <sub>T(RMS)</sub>	12	А		
Peak Non-Repetitive Surge Current (1/2 Cycle, Sine Wave, 60 Hz, T <sub>J</sub> = 90°C)	I <sub>TSM</sub>	100	А		
Circuit Fusing (t = 8.3 ms)	l <sup>2</sup> t	40	A <sup>2</sup> s		
Forward Peak Gate Power (Pulse Width ≤ 1.0 μs, T <sub>C</sub> = 90°C)	P <sub>GM</sub>	20	Watts		
Forward Average Gate Power (t = 8.3 ms, T <sub>C</sub> = 90°C)	P <sub>G(AV)</sub>	0.5	Watts		
Forward Peak Gate Current (Pulse Width ≤ 1.0 μs, T <sub>C</sub> = 90°C)	I <sub>GM</sub>	2.0	А		
Operating Junction Temperature Range	TJ	-40 to +125	°C		
Storage Temperature Range	T <sub>stg</sub>	-40 to +150	°C		

<sup>\*</sup>Indicates JEDEC Registered Data

1. V<sub>DRM</sub> and V<sub>RRM</sub> for all types can be applied on a continuous basis. Ratings apply for zero or negative gate voltage; however, positive gate voltage shall not be applied concurrent with negative potential on the anode. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the devices are exceeded.



## ON Semiconductor

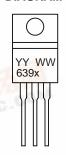
http://onsemi.com

## **SCRs** 12 AMPERES RMS 50 thru 800 VOLTS



#### **MARKING DIAGRAM**





Х	=	4, 5, 7 or 9
YY	=	Year
WW	=	Work Week

STYLE 3

PIN ASSIGNMENT				
1	Cathode			
2	Anode			
3	Gate			
4	Anode			

#### **ORDERING INFORMATION**

Device	Package	Shipping			
2N6394	TO220AB	500/Box			
2N6395	TO220AB	500/Box			
2N6397	TO220AB	500/Box			
2N6399	TO220AB	500/Box			

Preferred devices are recommended choices for future use and best overall value.



#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction to Case	$R_{\theta JC}$	2.0	°C/W
Maximum Lead Temperature for Soldering Purposes 1/8" from Case for 10 Seconds	TL	260	°C

#### ELECTRICAL CHARACTERISTICS (T<sub>C</sub> = 25°C unless otherwise noted.)

Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS	•				
*Peak Repetitive Forward or Reverse Blocking Current $(V_{AK} = Rated\ V_{DRM}\ or\ V_{RRM},\ Gate\ Open)$ $T_J = 25^{\circ}C$ $T_J = 125^{\circ}C$	I <sub>DRM</sub> , I <sub>RRM</sub>	_ _	_ _	10 2.0	μA mA
ON CHARACTERISTICS					
*Peak Forward On–State Voltage (Note 2.) (I <sub>TM</sub> = 24 A Peak)	V <sub>TM</sub>	-	1.7	2.2	Volts
*Gate Trigger Current (Continuous dc) (V <sub>D</sub> = 12 Vdc, R <sub>L</sub> = 100 Ohms)	I <sub>GT</sub>	-	5.0	30	mA
*Gate Trigger Voltage (Continuous dc) (V <sub>D</sub> = 12 Vdc, R <sub>L</sub> = 100 Ohms)	V <sub>GT</sub>	_	0.7	1.5	Volts
Gate Non-Trigger Voltage ( $V_D = 12 \text{ Vdc}, R_L = 100 \text{ Ohms}, T_J = 125^{\circ}\text{C}$ )	$V_{\sf GD}$	0.2	_	_	Volts
*Holding Current (V <sub>D</sub> = 12 Vdc, Initiating Current = 200 mA, Gate Open)	lн	-	6.0	50	mA
Turn-On Time $(I_{TM} = 12 \text{ A}, I_{GT} = 40 \text{ mAdc}, V_D = \text{Rated } V_{DRM})$	t <sub>gt</sub>	-	1.0	2.0	μѕ
Turn-Off Time ( $V_D$ = Rated $V_{DRM}$ ) ( $I_{TM}$ = 12 A, $I_R$ = 12 A) ( $I_{TM}$ = 12 A, $I_R$ = 12 A, $I_J$ = 125°C)	tq	- -	15 35	_ _	μs
DYNAMIC CHARACTERISTICS					
Critical Rate-of-Rise of Off-State Voltage Exponential (V <sub>D</sub> = Rated V <sub>DRM</sub> , T <sub>J</sub> = 125°C)	dv/dt	-	50	_	V/μs

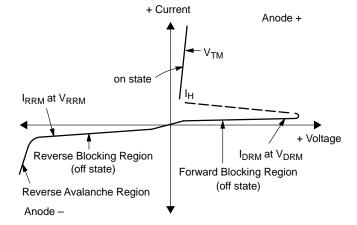
<sup>\*</sup>Indicates JEDEC Registered Data

http://opcomi.com

<sup>2.</sup> Pulse Test: Pulse Width  $\leq 300~\mu sec,~Duty~Cycle \leq 2\%.$ 

## **Voltage Current Characteristic of SCR**

Symbol	Parameter
V <sub>DRM</sub>	Peak Repetitive Off State Forward Voltage
I <sub>DRM</sub>	Peak Forward Blocking Current
$V_{RRM}$	Peak Repetitive Off State Reverse Voltage
I <sub>RRM</sub>	Peak Reverse Blocking Current
V <sub>TM</sub>	Peak On State Voltage
I <sub>H</sub>	Holding Current



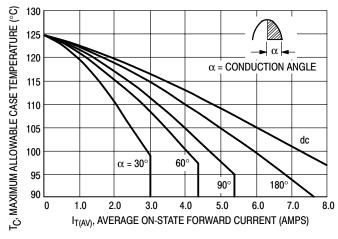


Figure 1. Current Derating

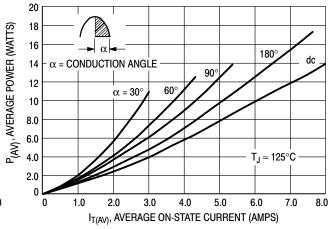
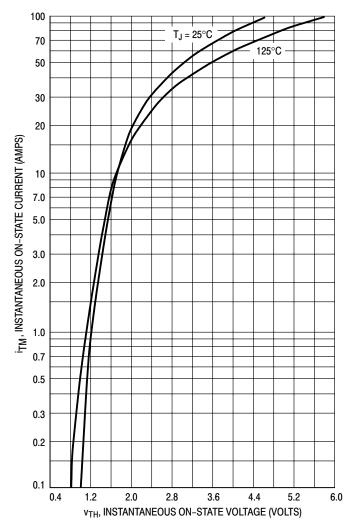


Figure 2. Maximum On-State Power Dissipation



100 1 CYCLE 95 ITSM, PEAK SURGE CURRENT (AMP) 90 85 80 75 70 T<sub>J</sub> = 125°C f = 60 Hz 65 SURGE IS PRECEDED AND 55 FOLLOWED BY RATED CURRENT 50 1.0 2.0 6.0 3.0 4.0 8.0 10 NUMBER OF CYCLES

Figure 3. On-State Characteristics

Figure 4. Maximum Non-Repetitive Surge Current

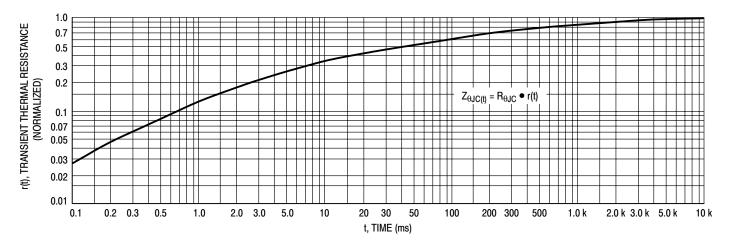
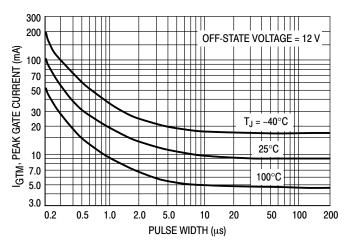


Figure 5. Thermal Response

#### TYPICAL CHARACTERISTICS

30

20



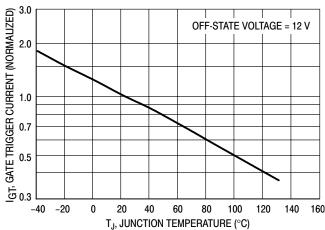
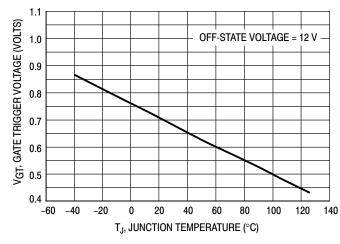


Figure 6. Typical Gate Trigger Current versus Pulse Width

Figure 7. Typical Gate Trigger Current versus Temperature

OFF-STATE VOLTAGE = 12 V



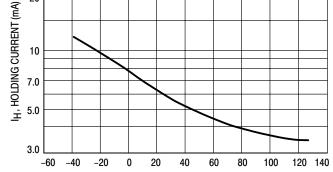


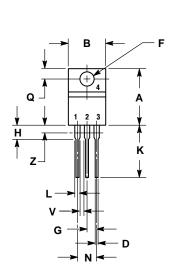
Figure 8. Typical Gate Trigger Voltage versus Temperature

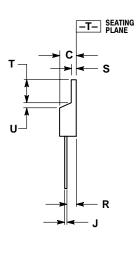
Figure 9. Typical Holding Current versus Temperature

T<sub>J</sub>, JUNCTION TEMPERATURE (°C)

#### **PACKAGE DIMENSIONS**

TO-220AB CASE 221A-07 ISSUE AA





- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.570	0.620	14.48	15.75
В	0.380	0.405	9.66	10.28
С	0.160	0.190	4.07	4.82
D	0.025	0.035	0.64	0.88
F	0.142	0.147	3.61	3.73
G	0.095	0.105	2.42	2.66
Н	0.110	0.155	2.80	3.93
J	0.014	0.022	0.36	0.55
K	0.500	0.562	12.70	14.27
L	0.045	0.060	1.15	1.52
N	0.190	0.210	4.83	5.33
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.15	1.39
T	0.235	0.255	5.97	6.47
υ	0.000	0.050	0.00	1.27
٧	0.045		1.15	
Z		0.080		2.04

STYLE 3:
PIN 1. CATHODE
2. ANODE
3. GATE
4. ANODE

# **Notes**

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